Lasertec

PRESS RELEASE

Lasertec Corporation
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(Code 6920 / Tokyo Stock Exchange, 1st Section)

Lasertec announces ROHM's decision to adopt the latest model of SICA

Yokohama, Japan, August 25, 2015 – **Lasertec Corporation** announced today that ROHM Co., Ltd. ("ROHM"), a leading company in power semiconductor device manufacturing, selected the latest model of Lasertec's SICA, SiC wafer inspection and review system.

ROHM provides various high-quality high-performance semiconductor devices that feature the state-of-the art process and design technologies for worldwide customers. Their corporate mission is "Quality is our top priority." ROHM is a global leader in the manufacture of power devices, especially of silicon carbide or SiC devices. ROHM has decided to introduce the latest model of SICA as part of its efforts to further enhance SiC device quality and production infrastructure.

Silicon carbide is a new material with properties suitable for power semiconductors and is viewed as a vitally important option for power device manufacturing. For mass production of SiC wafers and devices, further quality enhancement is expected. Amid various challenges, one of the critical factors in the mass production of high quality devices is to reduce defects that are commonly generated during grind and epitaxial processes. In this respect, it is extremely important to have a capability to accurately and quickly detect and categorize defects that affect device performance. Defects of interest (DOI) include not only scratches and epi-defects on wafer surface but also crystal-related defects such as basal plane dislocations (BPD) and stacking faults (SF) inside epi-layers. Eliminating these killer defects early in the process ensures high device yield in mass production.

The latest model of SICA incorporates a photoluminescence-based technology that enables the simultaneous detection of both surface defects and crystal defects at a significantly higher throughput. Lasertec will continue to pursue the development and advancement of defect inspection technologies in order to facilitate the further enhancement of power device quality and productivity.

About ROHM:

ROHM Co., Ltd. is an industry leader in system LSI, discrete components and module products utilizing the latest in semiconductor technology. ROHM's proprietary production system, which includes some of the most advanced automation technology, is a major factor in keeping it at the forefront of the electronic component manufacturing industry. As a vertically integrated company, ROHM is able to quickly and efficiently develop highly customized product in a cost effective manner for Consumer, Automotive, and Industrial sectors. http://www.rohm.com

About Lasertec:

As a leader in metrology and inspection tooling, Lasertec Corporation has been serving the needs of semiconductor, compound semiconductor, renewable energy, FPD and other high technology industries for many years. Since its beginning in 1960, Lasertec has been evolving and growing to keep pace with the world's rapidly expanding and changing high technology manufacturing requirements. In addition to the innovative technologies, Lasertec's global support infrastructure assures customers full satisfaction through high tool availability that maximizes the capital investment and device yield. For more information, go to: www.lasertec.co.jp/en.

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